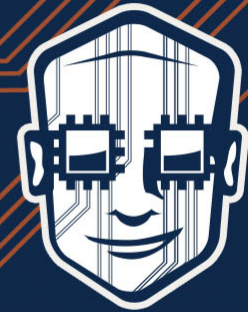


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Anritsu envision:ensure



S-PARAMETER QUALITY METRICS AND ANALYSIS TO MEASUREMENT CORRELATION





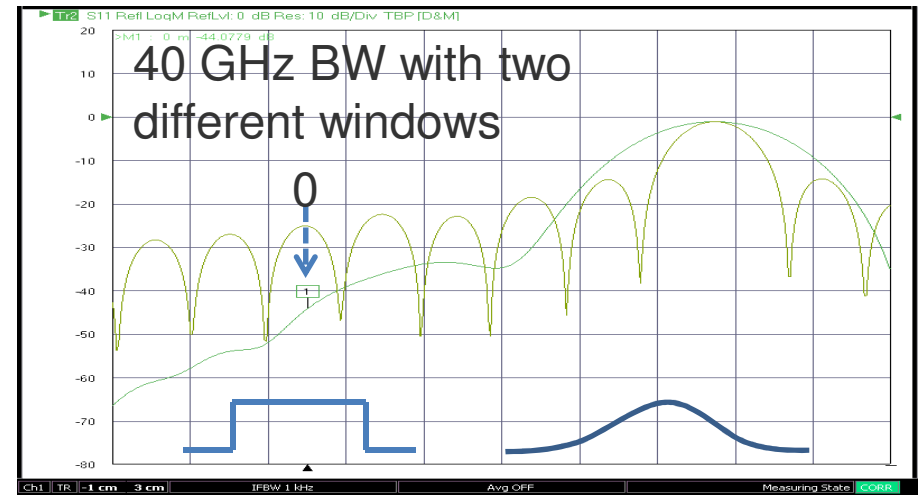
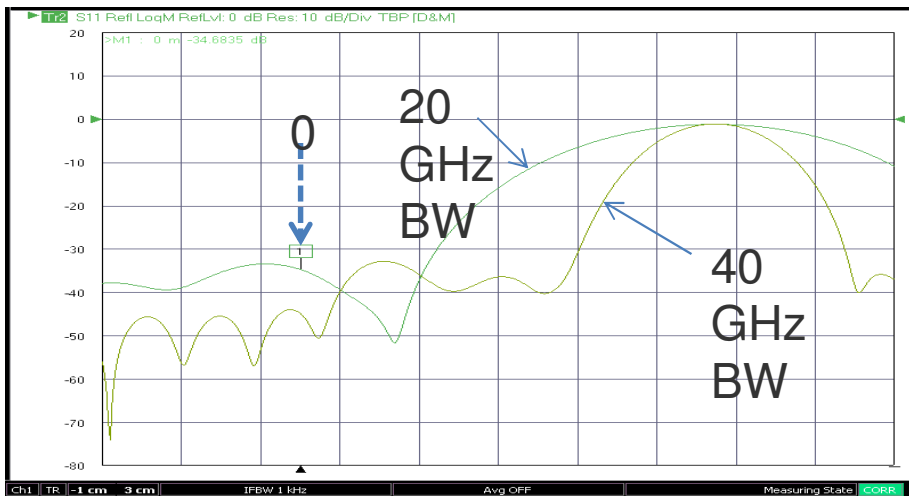
VNA Measurement S-Parameter Quality Metrics

S-Parameter Quality Metrics – Quality is important

- **Reciprocity**
 - Forward and reverse transmission are equal in both Magnitude and Phase
 - VNA's have excellent Reciprocity because of the architecture
 - More of an issue for TDR's and scopes than VNA because of trigger jitter
- **Passivity**
 - The channel must be passive and have loss
 - Calibration, De-embedding and contact repeatability can effect passivity
 - Verify with high quality low loss thru - airline (not cal thru!)
- **Causality**
 - All VNA's have causality issues.
 - Incomplete DC to Daylight data will cause S-Parameters to be non-causal.
 - This shows up as output energy occurring before the input stimulus in the time domain
 - Verify with S-Parameter CCW rotation on a polar chart in the frequency domain or look for energy in the time domain for $t < 0$

S-Parameter Metrics – Causality

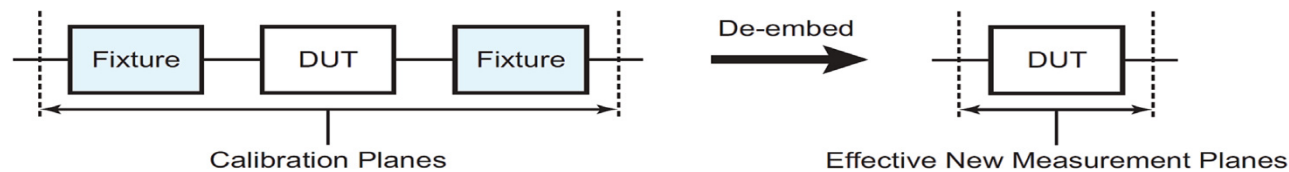
- Basic causality is always *impacted* by available finite bandwidth.
- Note the signal levels for $t < 0$.
- Bandwidth & Window Choices Affect Causality and Resolution



VNA BW (Frequency Span) effects causality

S-Parameter Metrics – Passivity

- Passivity problems occur when it appears a passive device has gain
- Receiver saturation issues can cause passivity issues during calibration or with the measurement
- De-embedding is often the problem. Small errors can cause large simulation errors.
- This is most prevalent in fixtures with high Insertion Loss and low Insertion Loss DUT's



- Having a wide range of extraction methods for de-embedding can be an advantage



Analysis to Measurement Correlation

Introduction

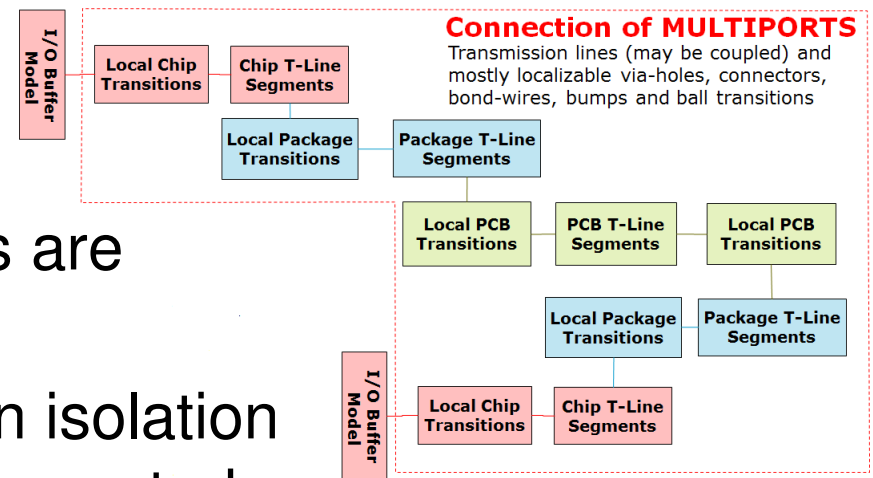


- Design of PCB and packaging interconnects for data links running at bitrates 28-32 Gbps and beyond is a challenging problem:
 - It requires electromagnetic analysis over extremely broad frequency bandwidth from DC to 40-50 GHz
 - No frequency-continuous dielectric models available from manufactures
 - No conductor roughness models available from manufacturers
 - Boards are not manufactured as designed – large variations and manipulations by manufacturers
 - Making accurate measurements over this bandwidth is very difficult
- Is it possible to design interconnects and have acceptable analysis to measurement correlation from DC up to 40-50 GHz systematically?

Analysis correlates with measurements if...



- 1) Quality of S-parameter models is ensured
- 2) Broadband material models are identified or confirmed
- 3) Simulation of all elements in isolation is possible or coupling is accounted
- 4) Models are validated with measurements



4 elements of design success – see App Notes #2013_03, 2013_05, 2014_05 at <http://www.simberian.com/AppNotes.php>

(1) Quality of S-parameter models

- Multiports are usually described with S-parameter models
 - Produced by circuit or electromagnetic simulators, VNAs and TDNAs in forms of Touchstone or BB SPICE models
- Very often such models have issues and may be not suitable for **consistent frequency and time domain analyses**
 - Bandwidth deficiency and discreteness
 - Model distortions leading to passivity, reciprocity and causality violations
- How to make sure that a model is suitable for analysis?
 - **Use formal quality metrics...**

*Quality estimation theory is covered in webinar #1 at
<http://www.simberian.com/Webinars.php>*

Good S-parameter Models of Interconnects



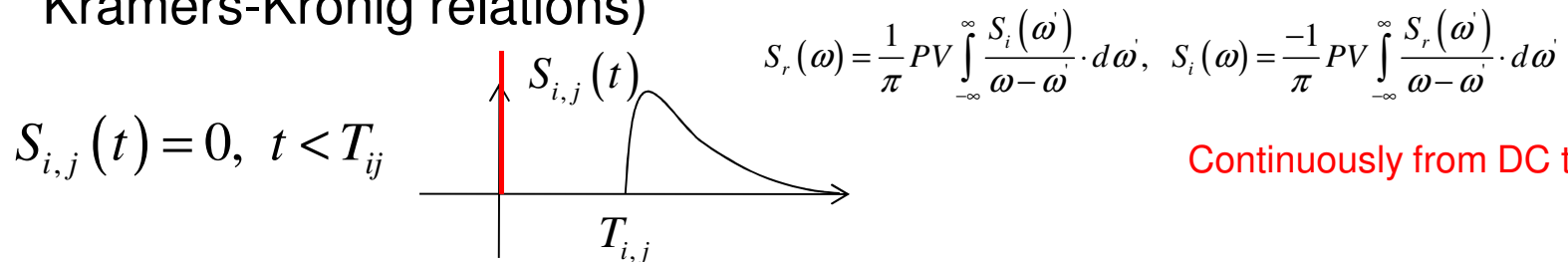
- Must have **sufficient bandwidth** matching signal spectrum
- Must be **appropriately sampled** to resolve all resonances
- Must be **passive** (do not generate energy)

$$P_{in} = \bar{a}^* \cdot [U - S^* S] \cdot \bar{a} \geq 0 \quad \Rightarrow \quad \text{eigenvals} [S^* \cdot S] \leq 1 \quad \text{Continuously from DC to infinity!}$$

- Must be **reciprocal** (linear reciprocal materials used in PCBs)

$$S_{i,j} = S_{j,i} \quad \text{or} \quad S = S^t$$

- Must be **causal** (have causal step or impulse response or satisfy Kramers-Kronig relations)



Preliminary Quality Metrics (0-100%)

First introduced at IBIS forum at DesignCon 2010

- Passivity Quality Measure:

$$PQM = \max \left[\frac{100}{N_{total}} \left(N_{total} - \sum_{n=1}^{N_{total}} PW_n \right), 0 \right] \%$$

$$PW_n = 0 \text{ if } PM_n < 1.00001; \text{ otherwise } PW_n = \frac{PM_n - 1.00001}{0.1}$$

$$PM_n = \sqrt{\max \left[\text{eigenvals} \left(S^*(f_n) \cdot S(f_n) \right) \right]}$$

- Reciprocity Quality Measure:

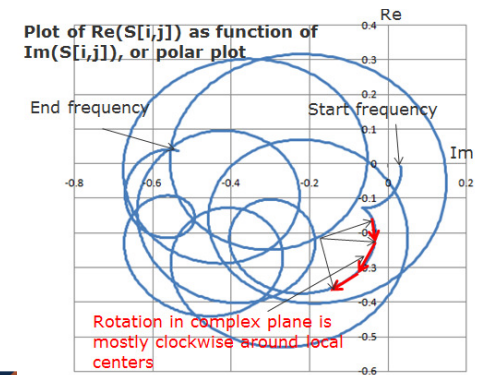
$$RQM = \max \left[\frac{100}{N_{total}} \left(N_{total} - \sum_{n=1}^{N_{total}} RW_n \right), 0 \right] \%$$

$$RW_n = 0 \text{ if } RM_n < 10^{-6}; \text{ otherwise } RW_n = \frac{RM_n - 10^{-6}}{0.1}$$

$$RM_n = \frac{1}{N_s} \sum_{i,j} |S_{i,j}(f_n) - S_{j,i}(f_n)|$$

- Causality Quality Measure:

Minimal ratio of clockwise rotation measure to total rotation measure in %



Preliminary Quality Metrics



- Brackets for Passivity, Reciprocity and Causality quality metrics

Metric/Model Icon	✔ - good	✔ - acceptable	❓ - inconclusive	✖ - bad
Passivity	[100, 99.9]	(99.9, 99]	(99, 80]	(80, 0]
Reciprocity	[100, 99.9]	(99.9, 99]	(99, 80]	(80, 0]
Causality	[100, 80]	(80, 50]	(50, 0]	-----

← For numerical models

Color code	Passivity (PQM)	Reciprocity (RQM)	Causality (CQM)
Green – good	[99.9, 100]	[99.9, 100]	[80, 100]
Blue – acceptable	[99, 99.9)	[99, 99.9)	[50, 80)
Yellow – inconclusive	[80, 99)	[80, 99)	[20, 50)
Red - bad	[0, 80)	[0, 80)	[0, 20)

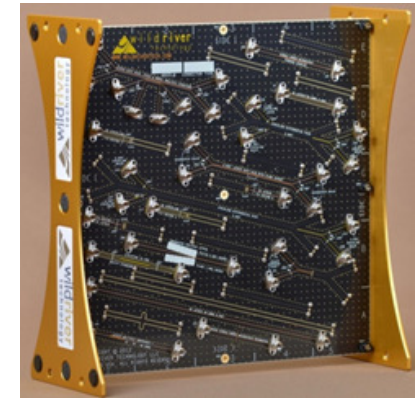
Example of preliminary quality evaluation in Simbeor Touchstone Analyzer



File name	Quality	Passivity	Reciprocity	Causality
C:\Repository\Simbeor\CMP-28_Simbeor_Kit_Rev4\CMP-28_Rev4\Touchstone_Files\2ndcal_d...				
Cal_Thru_3p74ns_p1_p2.s2p	-	100	99.8	99.9
Cal_Thru_3p74ns_p3_p4.s2p	-	100	99.6	99.9
cmp28_mstrp_diff_2inch_J38J37J34J33.s4p	-	100	99.8	71.4
cmp28_mstrp_diff_6inch_J46J45J42J41.s4p	-	100	99.8	73.1
cmp28_mstrp_diff_gnd_cutout_J59J60J55J56.s4p	-	100	99.8	89.7
cmp28_mstrp_diff_xtalk_J57J58J53J54.s4p	-	100	99.8	55.6
cmp28_mstrp_diff_xtalk_J57J64J53J72.s4p	-	100	99.9	77.2
cmp28_mstrp_diff_xtalk_J57J71J53J61.s4p	-	100	99.9	66.2
cmp28_mstrp_diff_xtalk_J57J72J53J64.s4p	-	100	99.9	67.8
cmp28_mstrp_diff_xtalk_J64J72J58J54.s4p	-	100	99.9	67.9
cmp28_mstrp_diff_xtalk_J71J58J61J54.s4p	-	100	99.9	66.9
cmp28_mstrp_diff_xtalk_J71J72J61J64.s4p	-	100	99.7	50
cmp28_mstrp_diff_xtalk_J72J58J64J54.s4p	-	100	99.9	63.6
cmp28_strpl_diff_2inch_J39J40J35J36.s4p	-	100	99.8	77.3
cmp28_strpl_diff_6inch_J47J48J43J44.s4p	-	100	99.9	78.3
C:\Repository\Simbeor\CMP-28_Simbeor_Kit_Rev4\CMP-28_Rev4\Touchstone_Files\3rdcal_1				
Cal_Thru_3p74ns_p1_p2_vias.s2p	-	100	99.4	99.9
Cal_Thru_3p74ns_p1_p2_vias_rpts2p	-	100	99.2	99.9
Cal_Thru_3p74ns_p3_p4_vias.s2p	-	100	99.5	100
cmp28_mstrp_diff_vias_J49J50J51J52.s4p	-	100	99.8	87.8
cmp28_mstrp_via_capacitive_p1J19_p2J20.s2p	-	100	99.2	94.8
cmp28_mstrp_via_inductive_p1J15_p2J16.s2p	-	100	99.6	96.6
cmp28_strpl_via_backdrilled_p1J14_p2J13.s2p	-	100	99.4	88
cmp28_strpl_via_capacitive_p1J18_p2J17.s2p	-	100	99.7	95.8

S-parameters measured for CMP-28 Channel Modeling Platform by Wild River Technology (from CMP-28 Simbeor Kit)

File name	Quality	Passivity	Reciprocity	Causality
C:\Repository\Simbeor\CMP-28_Simbeor_Kit_Rev4\CMP-28_Rev4\Touchstone_Files\1stcal_sin...				
cmp28_gnd_voids_p1J74_p2J75.s2p	-	100	99.4	93.1
cmp28_graduated_coplanar_p1J70_p2J69.s2p	-	100	99.5	84.4
cmp28_mstrp_2in_p1J1_p2J2.s2p	-	100	99.7	82.3
cmp28_mstrp_8inch_p1J4_p2J3.s2p	-	100	99.8	82.5
cmp28_mstrp_Beaty_25ohm_p1J25_p2J26.s2p	-	100	99.4	98.3
cmp28_mstrp_multiZ_p1J31_p2J32.s2p	-	100	99.3	98.5
cmp28_mstrp_p1J30_p2J29.s2p	-	100	99.8	98.6
cmp28_mstrp_resonator_p1J22_p2J22.s2p	-	100	99.7	99.4
cmp28_mstrp_whiskers_p1J68_p2J67.s2p	-	100	99.8	94
cmp28_strpl_2in_50ohm_p1J6_p2J5.s2p	-	100	99.1	82.3
cmp28_strpl_2in_Capacitive_p1J10_p2J09.s2p	-	100	99.5	93.8
cmp28_strpl_2in_Inductive_p1J12_p2J11.s2p	-	100	99.4	84.6
cmp28_strpl_8inch_p1J7_p2J8.s2p	-	100	99.7	74.7
cmp28_strpl_Beaty_25ohm_p1J28_p2J27.s2p	-	100	99.4	95.5
cmp28_strpl_resonator_p1J23_p2J24.s2p	-	100	99.4	98
cmp28_via_pathology_p1J65_p2J66.s2p	-	100	99.8	97.5



Live Demo...
Estimate quality
Plot S-parameters

Final model quality estimation with the rational approximation

- Accuracy of discrete S-parameters approximation with frequency-continuous macro-model, passive from DC to infinity

$$RMSE = \max_{i,j} \left[\sqrt{\frac{1}{N} \sum_{n=1}^N |S_{ij}(n) - S_{ij}(\omega_n)|^2} \right]$$

original tabulated data
rational approximation

$$S_{i,j}(i\omega) = \left[d_{ij} + \sum_{n=1}^{N_{ij}} \left(\frac{r_{ij,n}}{i\omega - p_{ij,n}} + \frac{r_{ij,n}^*}{i\omega - p_{ij,n}^*} \right) \right] \cdot e^{-s \cdot T_{ij}}$$

- Is used to estimate quality of the original data

$$Q = 100 \cdot \max(1 - RMSE, 0) \%$$

Model Icon/Quality	Quality Metric	RMSE
✔ - good	[99, 100]	[0, 0.01]
✔ - acceptable	[90, 99)	(0.01, 0.1]
⚠ - inconclusive	[50, 90)	(0.1, 0.5]
✘ - bad	[0, 50)	> 0.5
❓ - uncertain	[0,100], not passive or not reciprocal	

Rational model can be used for FD and TD analysis instead of the original data

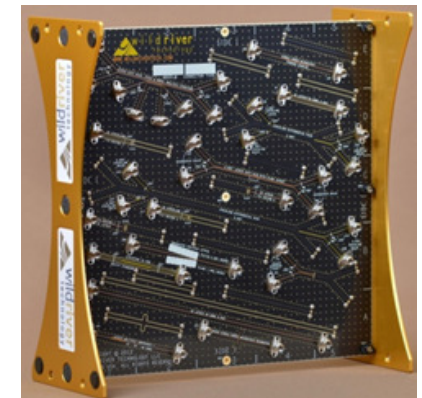
Example of FINAL quality evaluation in Simbeor Touchstone Analyzer



S-parameters measured for CMP-28 Channel Modeling Platform by Wild River Technology (from CMP-28 Simbeor Kit)

File name	Quality	Passivity	Reciprocity	Causality
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cmp28_mstrp_diff_2inch_J38J37J34J33.s4p	99.5	100	99.8	
cmp28_mstrp_diff_6inch_J46J45J42J41.s4p	99.6	100	99.8	
cmp28_mstrp_diff_gnd_cutout_J59J60J55J56.s4p	99.5	100	99.8	
cmp28_mstrp_diff_xtalk_J57J58J53J54.s4p	99.5	100	99.8	
cmp28_mstrp_diff_xtalk_J57J64J53J72.s4p	99.6	100	99.9	
cmp28_mstrp_diff_xtalk_J57J71J53J61.s4p	99.6	100	99.9	
cmp28_mstrp_diff_xtalk_J57J72J53J64.s4p	99.6	100	99.9	
cmp28_mstrp_diff_xtalk_J64J72J58J54.s4p	99.5	100	99.9	
cmp28_mstrp_diff_xtalk_J71J58J61J54.s4p	99.5	100	99.9	
cmp28_mstrp_diff_xtalk_J71J72J61J64.s4p	99.5	100	99.7	
cmp28_mstrp_diff_xtalk_J72J58J64J54.s4p	99.6	100	99.9	
cmp28_strpl_diff_2inch_J39J40J35J36.s4p	99.5	100	99.8	
cmp28_strpl_diff_6inch_J47J48J43J44.s4p	99.3	100	99.9	
C:\Repository\Simbeor\CMP-28_Simbeor_Kit_Rev4\CMP-28_Rev4\Touchstone...				
Cal_Thru_3p74ns_p1_p2_vias.s2p	96.5	100	99.4	
Cal_Thru_3p74ns_p1_p2_vias_rpts2p	96.8	100	99.2	
Cal_Thru_3p74ns_p3_p4_vias.s2p	97	100	99.5	
cmp28_mstrp_diff_vias_J49J50J51J52.s4p	98.9	100	99.8	
cmp28_mstrp_via_capacitive_p1J19_p2J20.s2p	99.6	100	99.2	
cmp28_mstrp_via_inductive_p1J15_p2J16.s2p	98.3	100	99.6	
cmp28_strpl_via_backdrilled_p1J14_p2J13.s2p	97.7	100	99.4	
cmp28_strpl_via_capacitive_p1J18_p2J17.s2p	93.4	100	99.7	

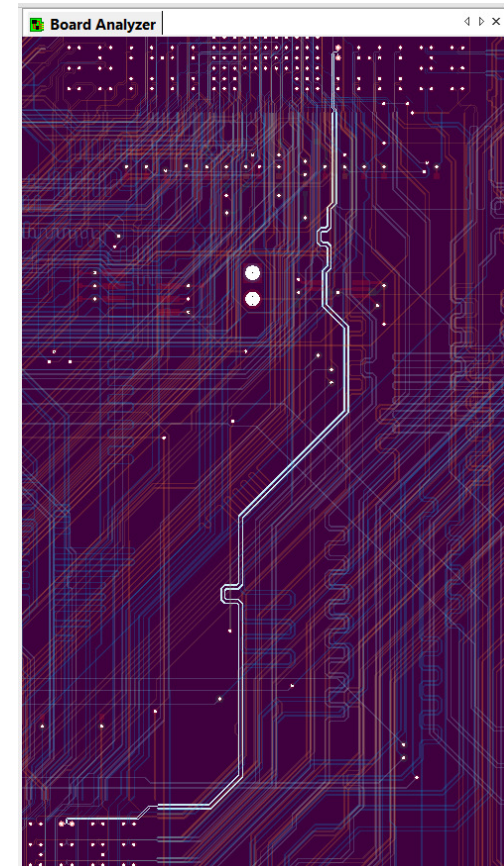
File name	Quality	Passivity	Reciprocity	Causality
C:\Repository\Simbeor\CMP-28_Simbeor_Kit_Rev4\CMP-28_Rev4\Touchstone_Files\1stc...				
cmp28_gnd_voids_p1J74_p2J75.s2p	99.5	100	99.4	-
cmp28_graduated_coplanar_p1J70_p2J69.s2p	99.7	100	99.5	-
cmp28_mstrp_2in_p1J1_p2J2.s2p	99.5	100	99.7	-
cmp28_mstrp_8inch_p1J4_p2J3.s2p	99.7	100	99.8	-
cmp28_mstrp_Beaty_25ohm_p1J25_p2J26.s2p	99.6	100	99.4	-
cmp28_mstrp_multiZ_p1J31_p2J32.s2p	99.6	100	99.3	-
cmp28_mstrp_p1J30_p2J29.s2p	99.6	100	99.8	-
cmp28_mstrp_resonator_p1J22_p2J22.s2p	99.7	100	99.7	-
cmp28_mstrp_whiskers_p1J68_p2J67.s2p	99.5	100	99.8	-
cmp28_strpl_2in_50ohm_p1J6_p2J5.s2p	99.6	100	99.1	-
cmp28_strpl_2in_Capacitive_p1J10_p2J09.s2p	99.5	100	99.5	-
cmp28_strpl_2in_Inductive_p1J12_p2J11.s2p	99.5	100	99.4	-
cmp28_strpl_8inch_p1J7_p2J8.s2p	99.6	100	99.7	-
cmp28_strpl_Beaty_25ohm_p1J28_p2J27.s2p	99.7	100	99.4	-
cmp28_strpl_resonator_p1J23_p2J24.s2p	99.6	100	99.4	-
cmp28_via_pathology_p1J65_p2J66.s2p	99.6	100	99.8	-



Live Demo...
Build RCM
Estimate quality
Compute TDR

(2) Broadband material models

- The largest part of interconnects are transmission line segments
- Models for transmission lines are usually constructed with a quasi-static or electromagnetic field solvers
 - Strip lines can be effectively analysed with quasi-static field solvers
 - Microstrip or CPW may require analysis with a full-wave solver to account for the high-frequency dispersion
- Accuracy of transmission line models is mostly defined by **availability of broadband dielectric and conductor roughness models**



PCB/Packaging material models

- Common dielectric models:**

Wideband Debye (aka Djordjevic-Sarkar or Swensson-Dermer):

$$\epsilon(f) = \epsilon_r(\infty) + \frac{\epsilon_{rd}}{(m_2 - m_1) \cdot \ln(10)} \cdot \ln \left[\frac{10^{m_2} + if}{10^{m_1} + if} \right]$$

Continuous-spectrum model; Requires specification of DK and LT at one frequency point (2 parameters)

Multi-pole Debye:
$$\epsilon(f) = \epsilon(\infty) + \sum_{n=1}^N \frac{\Delta\epsilon_n}{1 + i \frac{f}{fr_n}}$$

Requires specification of value at infinity and poles/residues or DK and LT at multiple frequency points (more than 2 parameters)

- Common conductor surface roughness models:**

Modified Hammerstad (2 parameters):

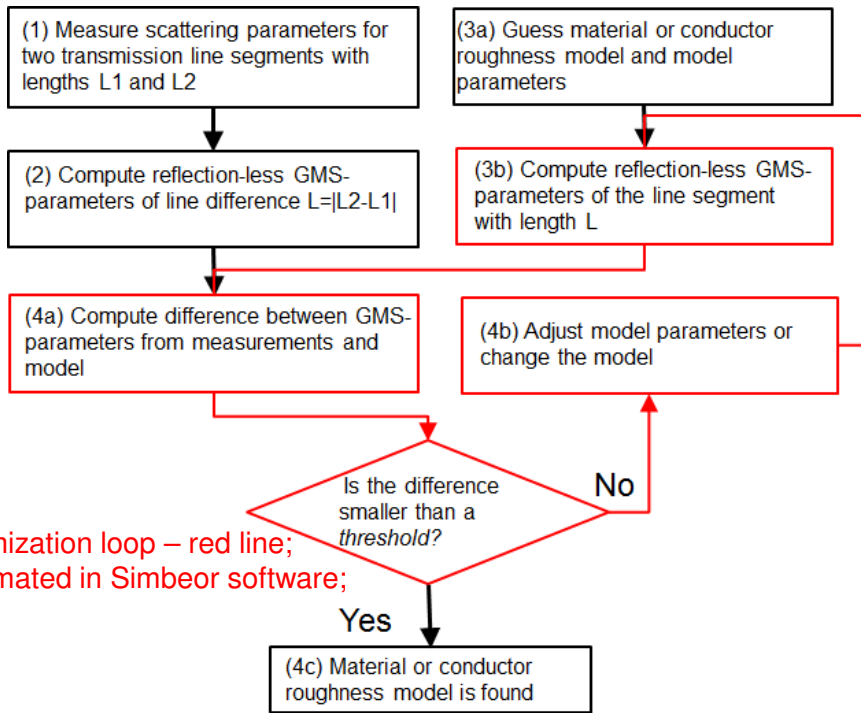
$$K_{rh} = 1 + \left(\frac{2}{\pi} \cdot \arctan \left[1.4 \left(\frac{\Delta}{\delta} \right)^2 \right] \right) \cdot (RF - 1)$$

Huray snowball (1-ball, 2 parameters):

$$K_{rhu} = 1 + \left(\frac{N \cdot 4\pi \cdot r^2}{A_{hex}} \right) / \left(1 + \frac{\delta}{r} + \frac{\delta^2}{2 \cdot r^2} \right)$$

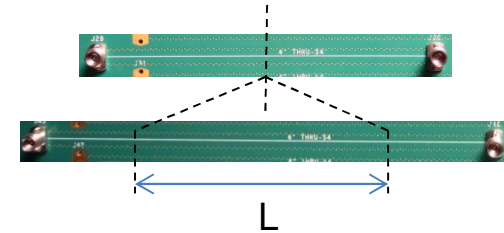
- Parameters for the models are not available and must be identified

Material model identification with GMS-parameters

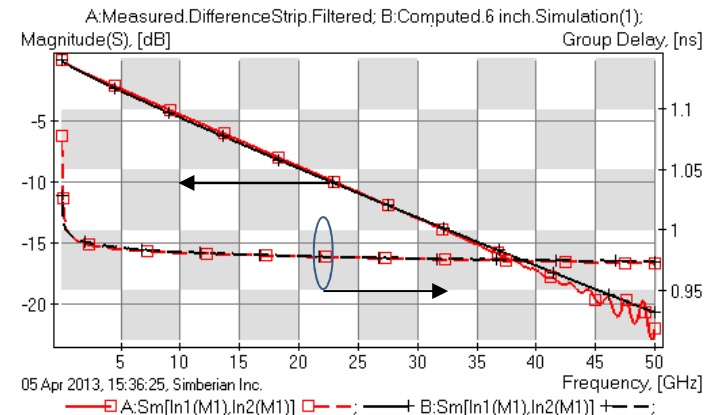


Optimization loop – red line;
Automated in Simbeor software;

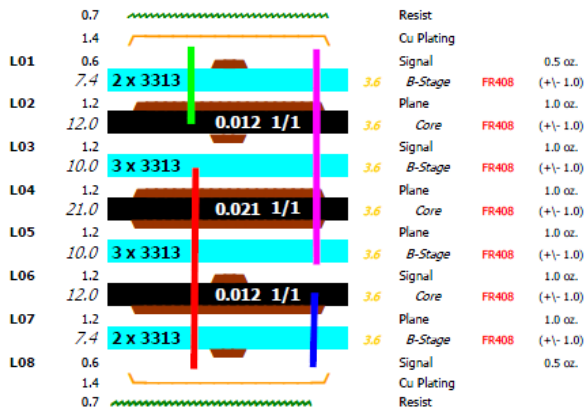
See App Notes #2014_02 and 2014_03 for details on identification with GMS-parameters at <http://www.simberian.com/AppNotes.php> and webinar #2 at <http://www.simberian.com/Webinars.php>



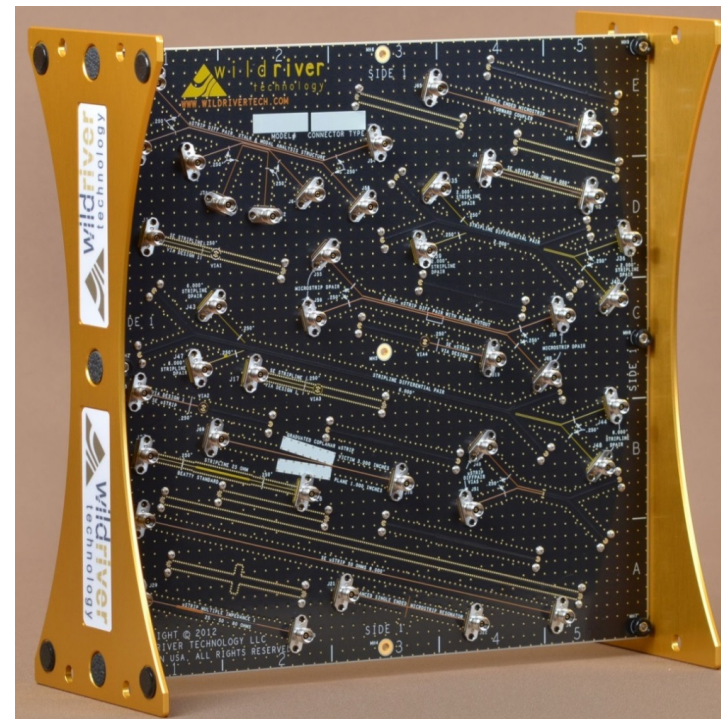
Applicable to dielectric and conductor roughness models;



Example of material model identification



CMP-28 validation board designed by Wild River Technology <http://wildrivertech.com/>

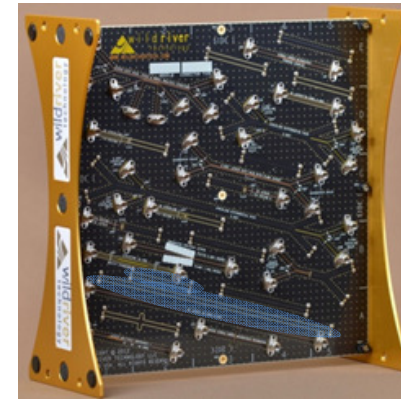


From Isola FR408HR specifications

Dk, Permittivity (Laminate & prepreg as laminated) Tested at 56% resin	A. @ 100 MHz (HP4285A)	3.69
	B. @ 1 GHz (HP4291A)	3.66
	C. @ 2 GHz (Bereskin Stripline)	3.67
	D. @ 5 GHz (Bereskin Stripline)	3.66
	E. @ 10 GHz (Bereskin Stripline)	3.65
Df, Loss Tangent (Laminate & prepreg as laminated) Tested at 56% resin	A. @ 100 MHz (HP4285A)	0.0094
	B. @ 1 GHz (HP4291A)	0.0117
	C. @ 2 GHz (Bereskin Stripline)	0.0120
	D. @ 5 GHz (Bereskin Stripline)	0.0127
	E. @ 10 GHz (Bereskin Stripline)	0.0125

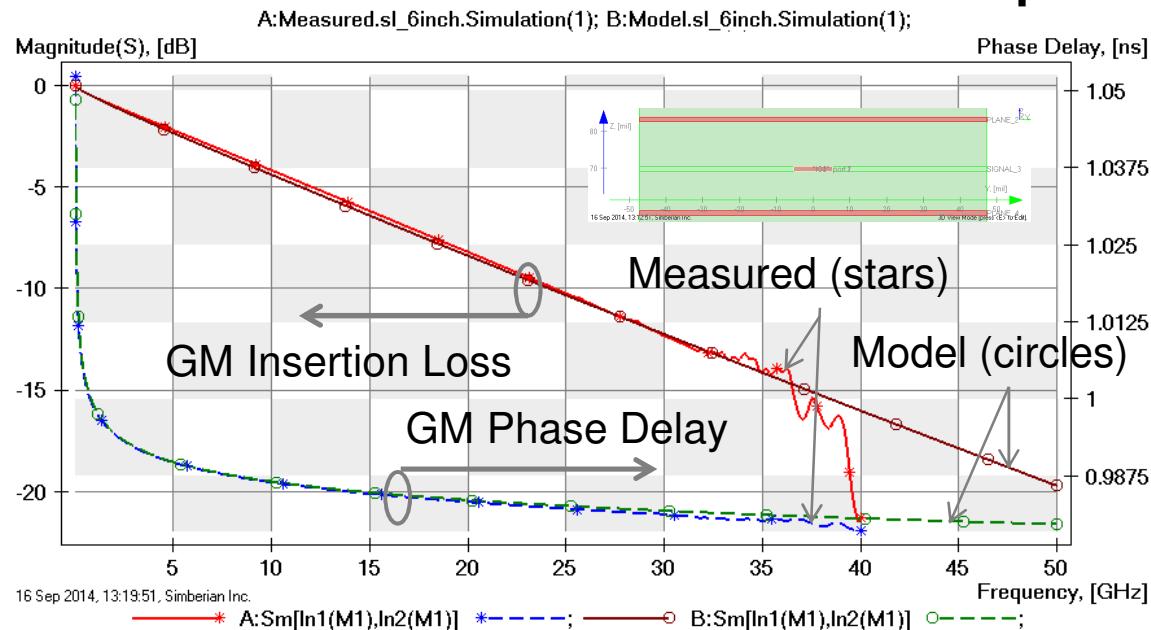
Use measured S-parameters for 2 strip (10.5 mil wide) and micro-strip (13.5 mil wide) segments (2 and 8 inch long);
Confirm with differential segments;

Models identified with strip line



GM - Generalized Modal (reflection-less);

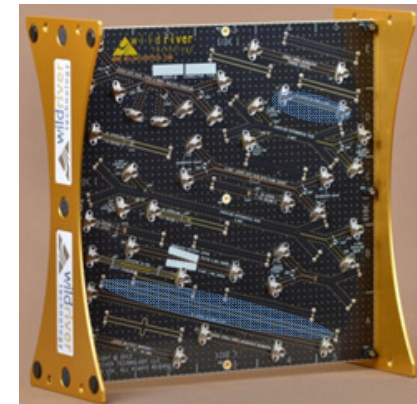
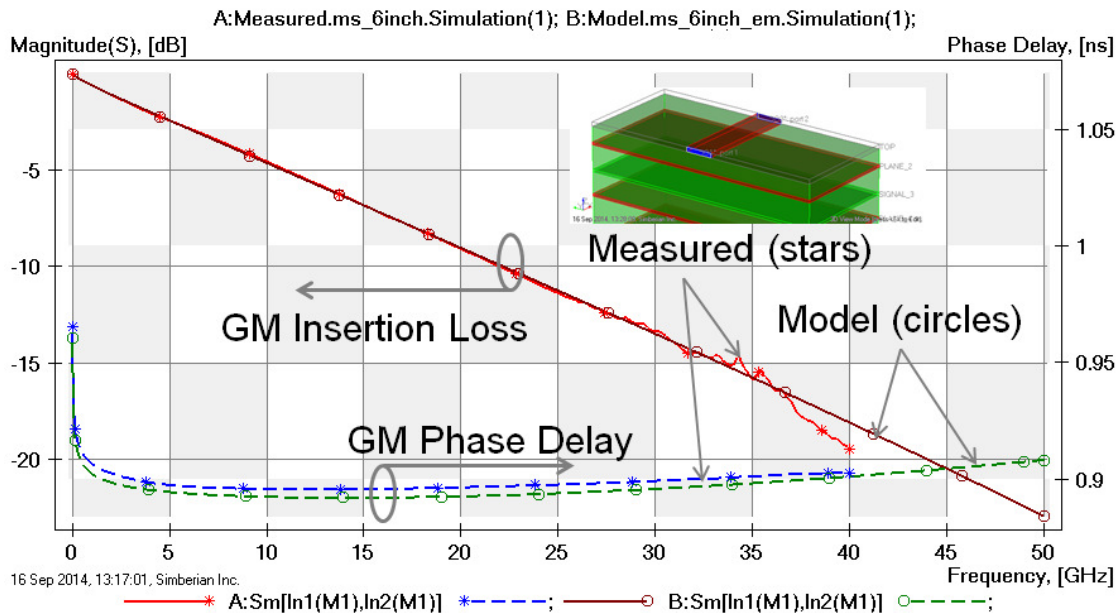
About 35 GHz useful bandwidth from the measured data due to mechanical differences;



GMS parameters computed from S-parameters measured for 2 and 8 inch strip line segments (red and blue lines) and modeled for 6 inch strip line segment (brown and green lines):
FR408HR model: Wideband Debye, Dk=3.815 (3.66), LT=0.0117 @ 1 GHz;
Conductor roughness model: Modified Hammerstad, SR=0.4 um, RF=2;

Models are usable up to 50 GHz!

Models identified with micro-strip line



GM - Generalized Modal (reflection-less);

About 35 GHz useful bandwidth from the measured data due to mechanical differences;

GMS parameters computed from S-parameters measured for 2 and 8 inch micro-strip line segments (red and blue lines) and modeled for 6 inch micro-strip line segment (brown and green lines):
 FR408HR model: Wideband Debye, $Dk=3.815$ (3.66), $LT=0.0117$ @ 1 GHz (same as for strip);
 Taiyo solder mask model: Wideband Debye, $Dk=3.85$ (3.9), $LT=0.02$ @ 1 GHz;
 Conductor roughness model: Modified Hammerstad, $SR=0.4$ μm , $RF=3.5$;

Models are usable up to 50 GHz!

(3) Modeling discontinuities in isolation



- A channel is typically composed with transmission lines of different types and transitions (vias, launches, connectors,...)
- The transitions may be reflective due to physical differences in cross-sections of the connected lines
 - The reflections cause additional losses and resonances and, thus, unwanted signal degradation
- The effect of the transitions can be accounted for with models built with a full-wave 3D analysis
- If such analysis is possible in isolation from the rest of the board up to a target frequency, the structure is called localizable
- **Only localizable transitions must be used to design predictable interconnects**

See how to check the localization at App Notes #2013_03, 2013_05 at <http://www.simberian.com/AppNotes.php>

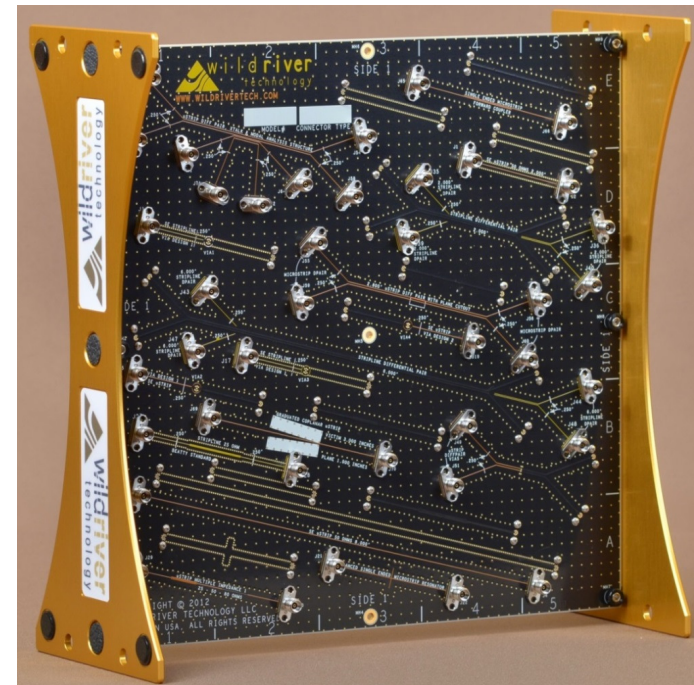
(4) Benchmarking or validation

- **How to make sure that simulation works? – Build validation boards!**
- Controlled board manufacturing is the key for success
 - Fiber type, resin content, copper roughness must be strictly specified or fixed!!!
 - Identify all manufacturing adjustments: stackup, etching compensation,...
- Include a set of structures to identify one material model at a time
 - Solder mask, core and prepreg, resin and glass, roughness, plating,...
- Include a set of structures to identify accuracy for transmission lines and typical discontinuities
 - Use identified material models for all structures on the board consistently
 - No tweaking - discrepancies should be investigated
- Use VNA measurements and compare both magnitude and phase (or group delay) of all S-parameters and optionally TDR and eye diagram

See more at: Y. Shlepnev, **Sink or swim at 28 Gbps**, The PCB Design Magazine, October 2014, p. 12-23.

Validation platforms simplify process

- CMP-28/32 Channel Modeling Platform was developed by Wild River Technology to promote systematic approach to interconnect analysis to measurement validation up to 40/50 GHz or up to 28/32 Gbps
 - **Contains 27 micro-strip and strip-line interconnect structures** equipped with 2.92 mm (CMP-28) and 2.4 mm (CMP-32) connectors and can be used to **validate signal integrity simulators or measurement technique**



Complete description of CMP-28/32 platforms with all results is available at http://www.simberian.com/Presentations/CMP-28_Simbeor_Kit_Guide.pdf

Demo of validation with Simbeor

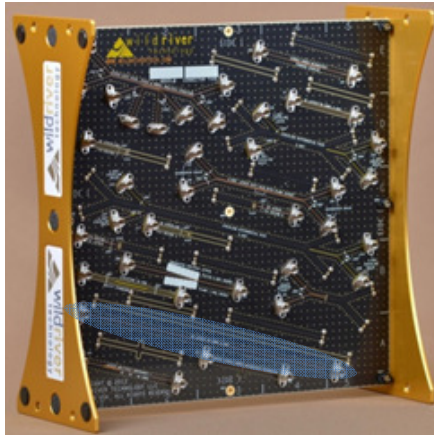


1. Measure and ensure quality of S-parameters (done)
2. Get all stackup and geometry adjustments from manufacturer or do cross-sectioning (done)
3. Identify or confirm material models (done)
4. Load board design and do post-layout analysis with or without connectors/launches

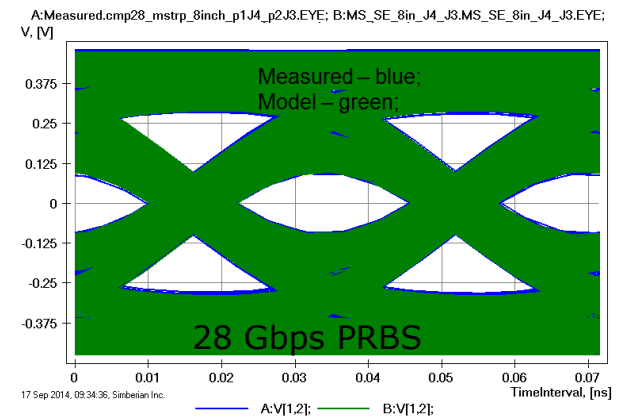
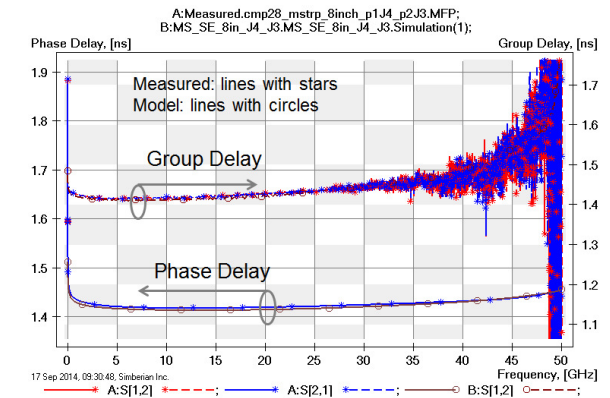
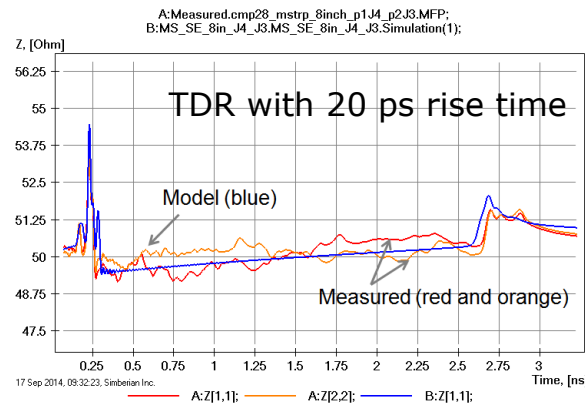
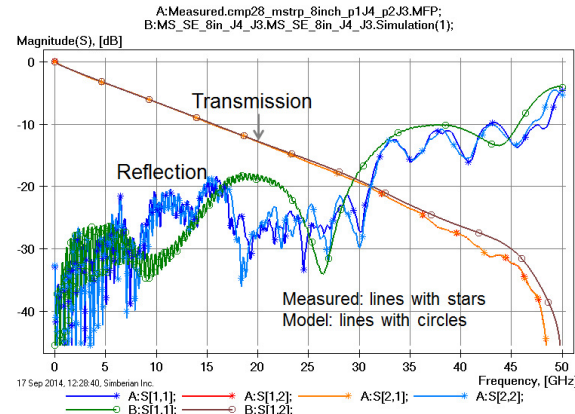
Example of validation



8-inch micro-strip line segment with launches and connectors



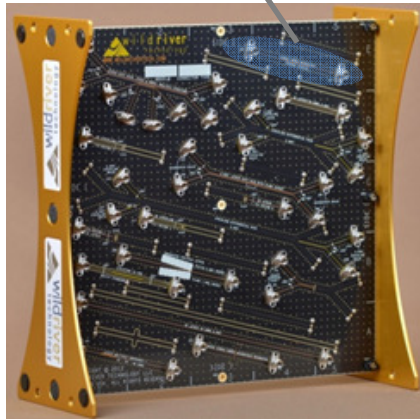
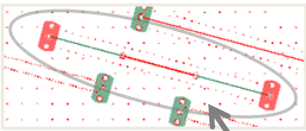
Trace width is reduced by 1 mil



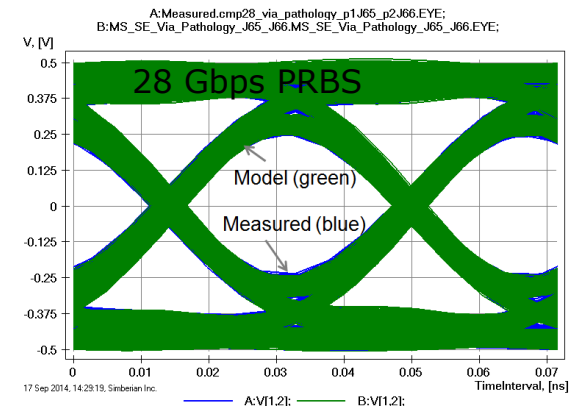
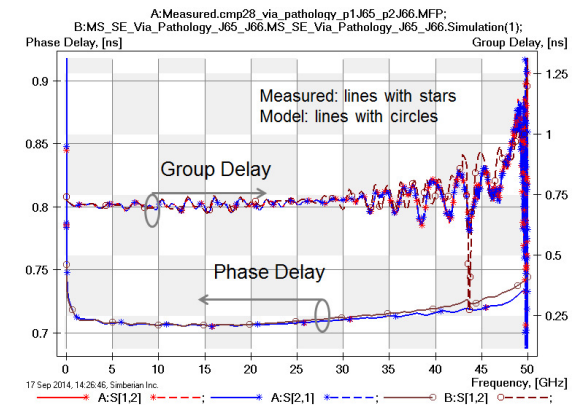
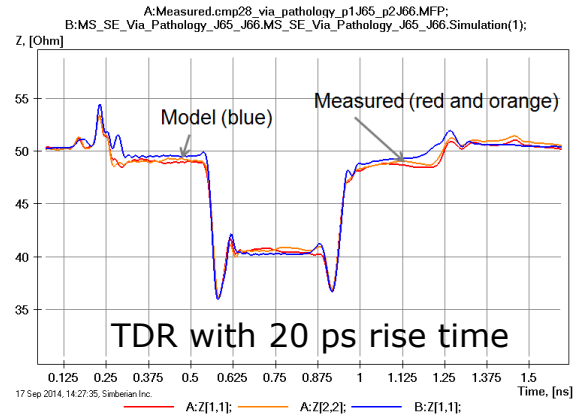
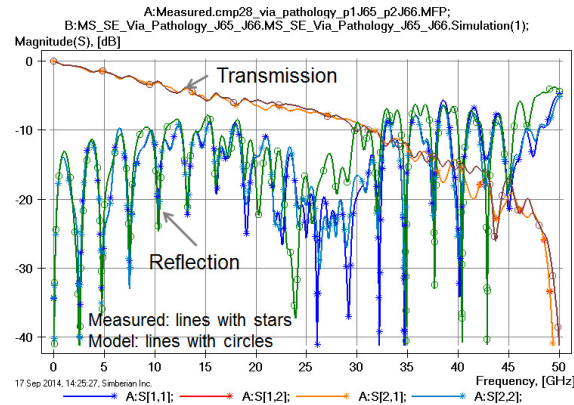
Example of validation



Micro-strip line segment with 2 capacitive vias with connectors and launches



Both narrow and wider sections widths are reduced by 1mil



What if simulation does not match measurements?



- ⊕ Verify quality metrics of the measured S-parameters
 - ⊕ Discard and re-measure if quality is not acceptable
- ⊕ Verify localization property of the link path (referencing and topology)
 - ⊕ Re-design non-localized elements
 - ⊕ Verify model ports if all elements are localized
- ⊕ Validate or identify material models
- ⊕ Control manufacturing or verify geometry (build or use validation boards)
 - ⊕ Cross-section t-lines and vias, do sensitivity analysis
- ⊕ Other things to check: model convergence, TDR spectrum, de-embedding...

Further resources

- Yuriy Shlepnev, Simberian Inc., www.simberian.com
shlepnev@simberian.com Tel: 206-409-2368
- **Webinars on decompositional analysis, S-parameters quality and material identification** <http://www.simberian.com/Webinars.php>
- Simberian web site and contacts www.simberian.com
- Demo-videos <http://www.simberian.com/ScreenCasts.php>
- App notes <http://www.simberian.com/AppNotes.php>
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